

## CLAIM AMENDMENTS

Please cancel Claims 1, 2, 4-33, 35-42, 46, 48, 54, 56, 92-95 as follows.

Claim 1-43 (cancelled)

Claim 43 (previously presented): A gate of a sealing device having a mold in which a semiconductor wafer having semiconductor elements on its surface is set in an area in order to form a resin layer on the semiconductor wafer by introducing a melted resin from a resin supplier, wherein the mold includes an upper mold and a lower mold, the gate being formed in the upper mold when the upper mold and the lower mold are closed, and being arranged outside the area, the gate introducing the melted resin into the mold wherein a depth of the gate is getting deeper from an outer end toward the inner end, which is closer to the area.

Claim 44 (previously presented): A gate as claimed in claim 43, wherein a width of the gate is getting expanded from the outer end toward the inner end.

Claim 45-95 (cancelled)